

WHAT IS CLAIMED IS:

1. A slurry for polishing copper-based metal containing a silica polishing material, an oxidizing agent, an amino acid, a triazole-based compound and water,

5 wherein a content ratio of said amino acid to said triazole-based compound (amino acid / triazole-based compound (weight ratio)) is 5 to 8.

10 2. The slurry for polishing copper-based metal according to Claim 1, wherein said amino acid is glycine.

15 3. The slurry for polishing copper-based metal according to Claim 1, wherein said triazole-based compound is 1, 2, 4-triazole or its derivative.

20 4. The slurry for polishing copper-based metal according to Claim 1, wherein a content of said triazole-based compound is not less than 0.05 % by weight but not greater than 0.5 % by weight.

25 5. The slurry for polishing copper-based metal according to Claim 1, wherein a pH value of said slurry is in a range of 5 to 7.

6. The slurry for polishing copper-based metal according to Claim 1, wherein said silica polishing

material is colloidal silica.